

## AMENDMENTS TO THE CLAIMS

1. (Currently Amended)      A circuit board, comprising:  
an electronic part having an electrode terminal on one surface thereof;  
a base layer;  
a first conductive circuit, manufactured by hardening a conductive paste material formed in  
a predetermined shape on said base layer;  
a first insulating layer, manufactured by hardening an insulating paste material formed on  
said base layer and said first conductive circuit, said first insulating layer having an opening therein;  
and  
a second insulating layer on said first insulating layer; and  
a second conductive circuit, manufactured by hardening a conductive paste material formed  
in a predetermined shape on said ~~first~~ second insulating layer;  
wherein said electronic part is within said opening such that said electronic part, but not said  
electrode terminal, is covered by said second insulating layer, and said electrode terminal is  
electrically connected to said second conductive circuit.
2. (Previously presented)      The circuit board according to claim 1, wherein  
said first insulating layer is only on a part of said base layer.
3. (Previously presented)      The circuit board according to claim 1, wherein  
said base layer comprises a film member.
4. (Previously presented)      The circuit board according to claim 3, further comprising:  
a plate member on a part of a surface of said base layer that is opposite to a surface of said  
base layer on which said first conductive circuit is formed.
5. (Previously presented)      The circuit board according to claim 1, wherein  
said base layer comprises a plate member.

6. (Previously presented) The circuit board according to claim 5, further comprising:  
another plate member,  
wherein at least said first insulating layer is positioned between said base layer and said  
another plate member.

7. (Previously presented) The circuit board according to claim 1, further comprising:  
a connection opening in said first insulating layer on said first conductive circuit,  
wherein said first conductive circuit and said second conductive circuit are electrically  
connected to each other via said connection opening.

8. (Currently amended) The circuit board according to claim 1, further comprising:  
a resistance layer, formed by hardening a resistance paste material coated onto one of said  
base layer and said ~~first~~second insulating layer,  
wherein said resistance layer forms a resistor electrically connected to one of said first  
conductive circuit and said second conductive circuit.

9. (Previously presented) The circuit board according to claim 1, further comprising:  
a resistance layer, formed by hardening a resistance paste material applied to a resistance  
opening in said first insulating layer,  
wherein said resistance layer forms a resistor electrically connected to said first conductive  
circuit and said second conductive circuit.

10. (Currently Amended) The circuit board according to claim 1, further comprising:  
a dielectric layer, formed by hardening a dielectric paste material coated onto one of said base  
layer and said ~~first~~second insulating layer,  
wherein said dielectric layer forms a capacitor electrically connected to one of said first  
conductive circuit and said second conductive circuit.

11. (Previously presented) The circuit board according to claim 1, further comprising:  
a dielectric layer, formed by hardening a dielectric paste material applied to a dielectric opening in said first insulating layer,

wherein said dielectric layer forms a capacitor electrically connected to said first conductive circuit and said second conductive circuit.

12. (Previously presented) The circuit board according to claim 1, wherein  
a part of one of said first conductive circuit and said second conductive circuit forms an inductor.

13. (Previously presented) The circuit board according to claim 1, wherein  
one of said first conductive circuit and said second conductive circuit is connected to metallic wiring formed by any one of a depositing, plating and sputtering process.

14. (Currently Amended) The circuit board according to claim 13, wherein  
said electronic part comprises a bare chip IC, and  
said metallic wiring is connected to an electrode terminal of a bare chip IC.

15. (Previously presented) The circuit board according to claim 1, further comprising:  
electronic parts mounted on said second conductive circuit.

16. (Withdrawn) A method of manufacturing a circuit board, comprising:  
forming a first conductive circuit by hardening a conductive paste material formed in a predetermined shape on a base layer;

forming a first insulating layer by hardening an insulating paste material coated onto said base layer and said first conductive circuit; and

forming a second conductive circuit by hardening a conductive paste material formed in a predetermined shape on said first insulating layer.

17. (Withdrawn) The method of manufacturing a circuit board according to claim 16, wherein

forming a first insulating layer comprises forming a first insulating layer having a connection opening in that portion of said first insulating layer that is on said first conductive circuit, and

forming a second conductive circuit comprises filling said conductive paste material into said connection opening such that said first conductive circuit and said second conductive circuit are interconnected by said conductive paste material filled into said connection opening.

18. (Withdrawn) The method of manufacturing a circuit board according to claim 16, further comprising:

forming a resistive layer by hardening a resistance paste material coated onto one of said base layer and said first insulating layer,

such that a resistor electrically connecting said first conductive circuit to said second conductive circuit is formed.

19. (Withdrawn) The method of manufacturing a circuit board according to claim 16, further comprising:

forming a resistance opening in said first insulating layer on said first conductive circuit layer; and

forming a resistive layer by hardening a resistance paste material applied to said resistance opening,

such that a resistor electrically connected to said first conductive circuit and said second conductive circuit is formed.

20. (Withdrawn) The method of manufacturing a circuit board according to claim 16, further comprising:

forming a dielectric layer by hardening a dielectric paste material coated onto one of said base layer and said first insulating layer,

such that a capacitor electrically connecting said first conductive circuit to said second

conductive circuit is formed.

21. (Withdrawn) The method of manufacturing a circuit board according to claim 16, further comprising:

forming a dielectric opening in said first insulating layer on said first conductive circuit; and  
forming a dielectric layer by hardening a dielectric paste material applied to said dielectric opening,

such that a capacitor electrically connected to said first conductive circuit and said second conductive circuit is formed.

22. (Withdrawn) The method of manufacturing a circuit board according to claim 16, further comprising:

forming an inductor on a part of one of said first conductive circuit and said second conductive circuit.

23. (Withdrawn) A circuit board, comprising:  
a part arrangement layer with an electronic part disposed in such a manner that an electrode terminal of said electronic part is exposed on one surface of said electronic part; and

a second conductive circuit formed in a predetermined shape, said second conductive circuit being electrically connected to said electrode terminal;

wherein said part arrangement layer includes

(i) a first conductive circuit, formed by hardening a conductive paste material coated in a predetermined shape, and

(ii) an insulating layer, formed by hardening an insulating paste material coated onto said first conductive circuit, said insulating layer being formed in such a manner that said electrode terminal is exposed on a surface of said insulating layer.

24. (Withdrawn) The circuit board according to claim 23, further comprising:  
a connection opening in said insulating layer on said first conductive circuit, and said first

conductive circuit

wherein said first conductive circuit and said second conductive circuit are electrically connected with each other via said connection opening.

25. (Withdrawn) The circuit board of claim 23, wherein said part arrangement layer further includes other electronic parts electrically connected to said first conductive circuit.

26. (Withdrawn) The circuit board of claim 23, further comprising:  
a base layer which supports said part arrangement layer, said base layer being adhered via an adhesive to a surface of said electronic part that is opposite to said one surface of said electronic part.

27. (Withdrawn) The circuit board of claim 26, wherein said part arrangement layer is only on a part of said base layer.

28. (Withdrawn) The circuit board of claim 26, wherein said base layer comprises a film member.

29. (Withdrawn) The circuit board of claim 28, further comprising:  
a plate member connected to a part of a surface of said part arrangement layer that is opposite to a surface of said part arrangement layer that is connected to said base layer.

30. (Withdrawn) The circuit board of claim 26, wherein said base layer comprises a plate member.

31. (Withdrawn) The circuit board of claim 30, further comprising:  
another plate member,  
wherein said part arrangement layer is sandwiched between said base layer and said another

plate member.

32. (Withdrawn) The circuit board of claim 23, wherein one of said first conductive circuit and said second conductive circuit is connected to metallic wiring formed by any one of a depositing, plating and sputtering process.

33. (Withdrawn) The circuit board of claim 32, wherein said electronic part comprises a semiconductor integrated circuit element of bare chip configuration, and said metallic wiring is formed so as to connect an electrode terminal of said semiconductor integrated circuit element to said second conductive circuit.

34. (Withdrawn) The circuit board of claim 23, wherein said part arrangement layer is further provided with other electronic parts.

35. (Withdrawn) A method of manufacturing a circuit board, comprising:  
forming a part arrangement layer having a part opening,  
wherein forming said part arrangement layer includes:  
(i) forming a first conductive circuit by hardening a conductive paste material formed in a predetermined shape,  
(ii) forming a first insulating layer by hardening an insulating paste material, coated in a shape defining said part opening, on a predetermined portion of a surface including said first conductive circuit,  
(iii) inserting an electronic part into said part opening in such a manner that an electrode terminal is exposed, and  
(iv) forming a second insulating layer by hardening an insulating paste material coated onto said electronic part and said first insulating layer in such a manner that at least a surface of said electrode terminal is exposed; and  
forming a second conductive circuit in a predetermined shape on said first part arrangement

layer and said electrode terminal.

36. (Withdrawn) The method of manufacturing a circuit board according to claim 35, wherein

forming a second conductive circuit comprises hardening a conductive paste coated onto said first part arrangement layer and said electrode terminal.

37. (Withdrawn) The method of manufacturing a circuit board according to claim 36, wherein

forming a first insulating layer comprises forming a first insulating layer having a connection opening in a portion of said first insulating layer that is on said first conductive circuit, and

forming a second conductive circuit comprises filling said conductive paste into said connection opening such that said first conductive circuit and said second conductive circuit are electrically interconnected by hardening said conductive paste material.

38. (Withdrawn) The method of manufacturing a circuit board according to claim 35, further comprising:

forming a second part opening that extends through said part arrangement layer and said second conductive circuit; and

inserting a second electronic part, that is thicker than said first electronic part, into said second part opening.

39. (Withdrawn) The method of manufacturing a circuit board according to claim 35, wherein

forming a part arrangement layer comprises forming said part arrangement layer on a film base layer, and further comprising:

securing said electronic part within said part opening via adhesive.